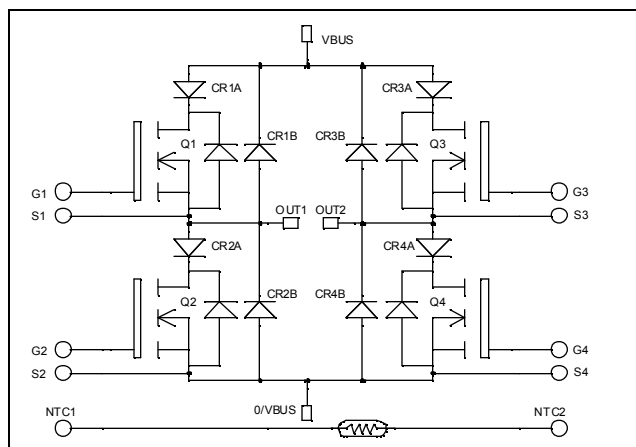


Full bridge Series & parallel diodes MOSFET Power Module

$$V_{DSS} = 1000V$$

$$R_{DSon} = 450m\Omega \text{ max @ } T_j = 25^\circ C$$

$$I_D = 18A \text{ @ } T_c = 25^\circ C$$



Application

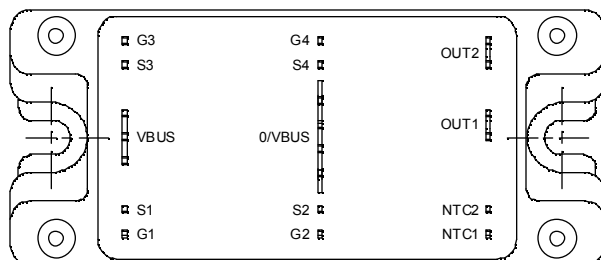
- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

Features

- Power MOS 7[®] MOSFETs
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
 - Symmetrical design
 - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile



Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V_{DSS}	Drain - Source Breakdown Voltage	1000	V
I_D	Continuous Drain Current	$T_c = 25^\circ C$ 18	A
		$T_c = 80^\circ C$ 14	
I_{DM}	Pulsed Drain current	72	
V_{GS}	Gate - Source Voltage	± 30	V
R_{DSon}	Drain - Source ON Resistance	450	m Ω
P_D	Maximum Power Dissipation	$T_c = 25^\circ C$ 357	W
I_{AR}	Avalanche current (repetitive and non repetitive)	18	A
E_{AR}	Repetitive Avalanche Energy	50	mJ
E_{AS}	Single Pulse Avalanche Energy	2500	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
BV_{DSS}	Drain - Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	1000			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS} = 0V, V_{DS} = 1000V, T_j = 25^\circ\text{C}$			100	μA
		$V_{GS} = 0V, V_{DS} = 800V, T_j = 125^\circ\text{C}$			500	
$R_{DS(on)}$	Drain - Source on Resistance	$V_{GS} = 10V, I_D = 9A$			450	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.5mA$	3		5	V
I_{GSS}	Gate - Source Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$			± 100	nA

Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C_{iss}	Input Capacitance	$V_{GS} = 0V$		4350		pF
C_{oss}	Output Capacitance	$V_{DS} = 25V$		715		
C_{rss}	Reverse Transfer Capacitance	$f = 1MHz$		120		
Q_g	Total gate Charge	$V_{GS} = 10V$		154		nC
Q_{gs}	Gate - Source Charge	$V_{Bus} = 500V$		26		
Q_{gd}	Gate - Drain Charge	$I_D = 18A$		97		
$T_{d(on)}$	Turn-on Delay Time	Inductive switching @ 125°C $V_{GS} = 15V$ $V_{Bus} = 667V$ $I_D = 18A$ $R_G = 5\Omega$		10		ns
T_r	Rise Time			12		
$T_{d(off)}$	Turn-off Delay Time			121		
T_f	Fall Time			35		
E_{on}	Turn-on Switching Energy ❶	Inductive switching @ 25°C $V_{GS} = 15V, V_{Bus} = 667V$ $I_D = 18A, R_G = 5\Omega$		639		μJ
E_{off}	Turn-off Switching Energy ❷			380		
E_{on}	Turn-on Switching Energy ❶	Inductive switching @ 125°C $V_{GS} = 15V, V_{Bus} = 667V$ $I_D = 18A, R_G = 5\Omega$		1046		μJ
E_{off}	Turn-off Switching Energy ❷			451		

❶ E_{on} includes diode reverse recovery.

❷ In accordance with JEDEC standard JESD24-1.

Series diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	Maximum Average Forward Current	50% duty cycle, $T_c = 85^\circ\text{C}$		30		A
V_F	Diode Forward Voltage	$I_F = 30A$		1.1	1.15	V
		$I_F = 60A$		1.4		
		$I_F = 30A, T_j = 125^\circ\text{C}$		0.9		
t_{rr}	Reverse Recovery Time	$I_F = 30A, V_R = 133V, di/dt = 200A/\mu s, T_j = 25^\circ\text{C}$		24		ns
		$T_j = 125^\circ\text{C}$		48		
Q_{rr}	Reverse Recovery Charge	$I_F = 30A, V_R = 133V, di/dt = 200A/\mu s, T_j = 25^\circ\text{C}$		33		nC
		$T_j = 125^\circ\text{C}$		150		

Parallel diode ratings and characteristics

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	Maximum Average Forward Current	50% duty cycle	$T_c = 65^\circ\text{C}$		30		A
V_F	Diode Forward Voltage	$I_F = 30\text{A}$			1.9	2.3	V
		$I_F = 60\text{A}$			2.2		
		$I_F = 30\text{A}$	$T_j = 125^\circ\text{C}$		1.7		
t_{rr}	Reverse Recovery Time	$I_F = 30\text{A}$ $V_R = 667\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		290		ns
			$T_j = 125^\circ\text{C}$		390		
Q_{rr}	Reverse Recovery Charge	$I_F = 30\text{A}$ $V_R = 667\text{V}$ $di/dt = 200\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$		670		nC
			$T_j = 125^\circ\text{C}$		2350		

Thermal and package characteristics

Symbol	Characteristic			Min	Typ	Max	Unit
R_{thJC}	Junction to Case	Transistor				0.35	$^\circ\text{C}/\text{W}$
		Diode				1.2	
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t=1\text{ min}$, $I_{isol}<1\text{mA}$, 50/60Hz			2500			V
T_J	Operating junction temperature range			-40		150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range			-40		125	
T_C	Operating Case Temperature			-40		100	
Torque	Mounting torque	To Heatsink	M5			4.7	N.m
Wt	Package Weight					160	g

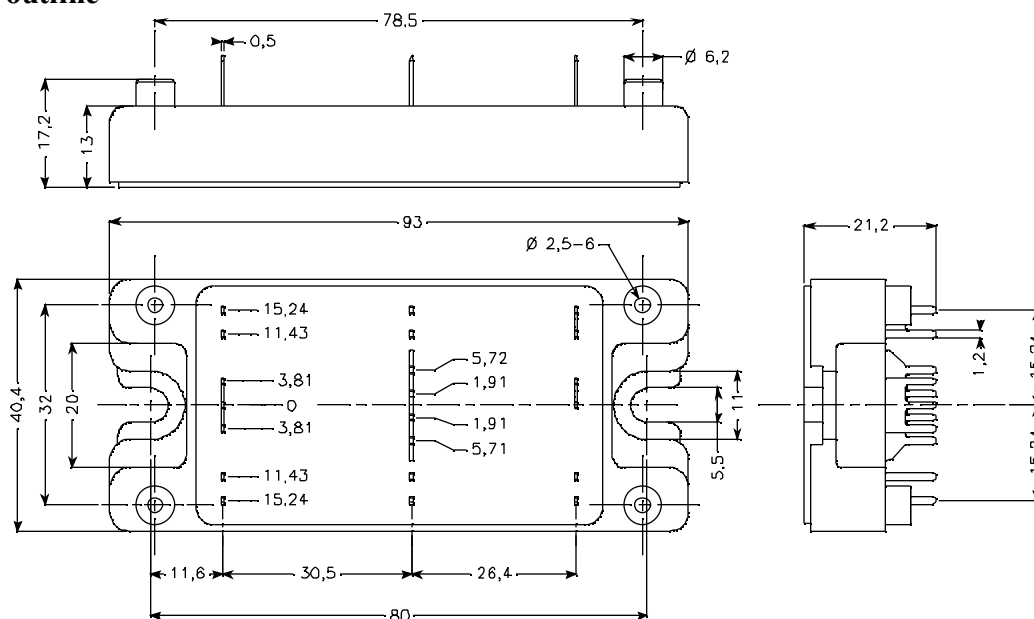
Temperature sensor NTC

Symbol	Characteristic	Min	Typ	Max	Unit
R_{25}	Resistance @ 25°C		68		$\text{k}\Omega$
$B_{25/85}$	$T_{25} = 298.16\text{ K}$		4080		K

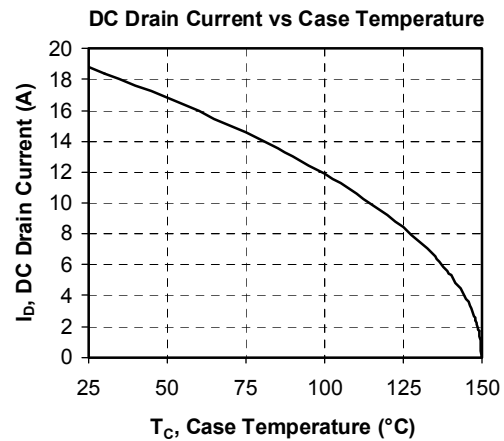
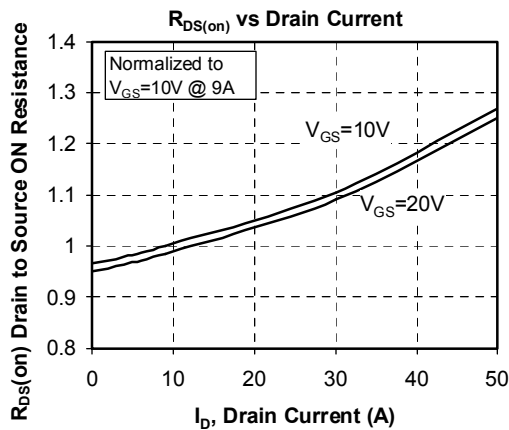
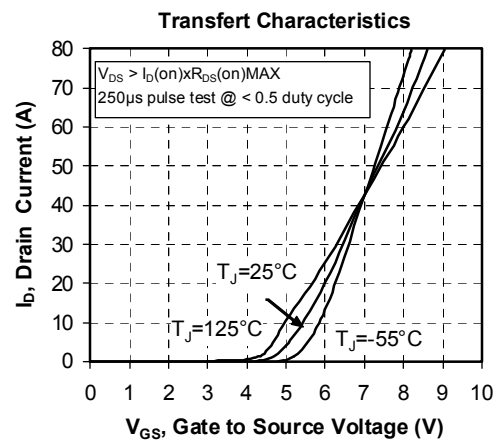
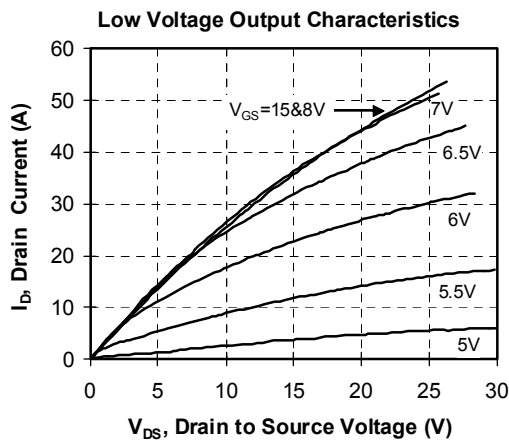
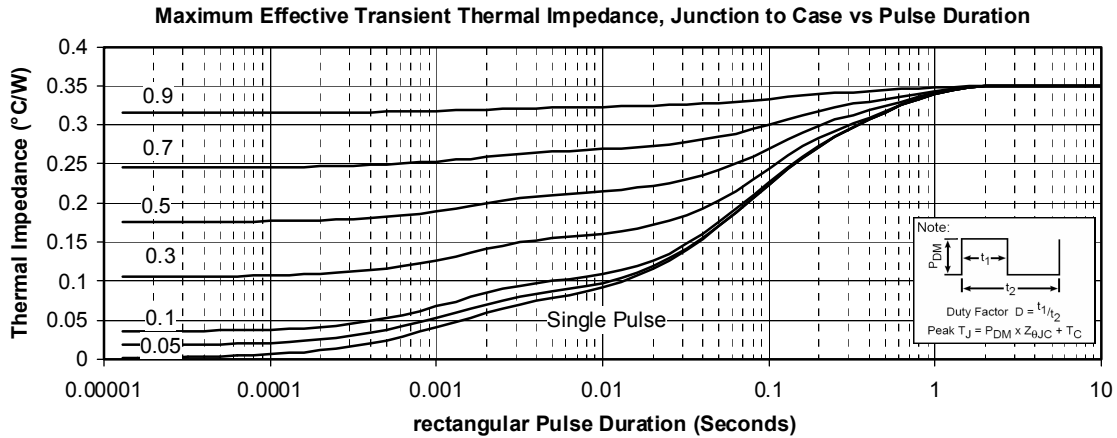
$$R_T = \frac{R_{25}}{\exp \left[B_{25/85} \left(\frac{1}{T_{25}} - \frac{1}{T} \right) \right]}$$

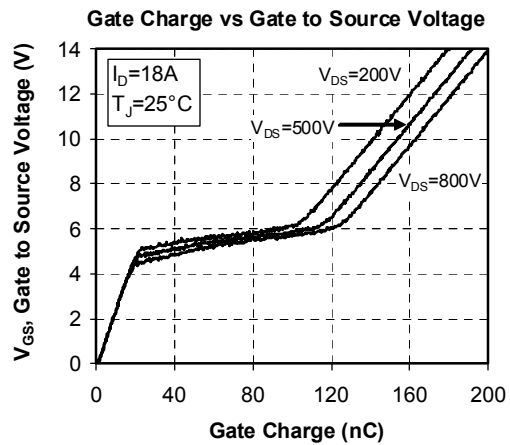
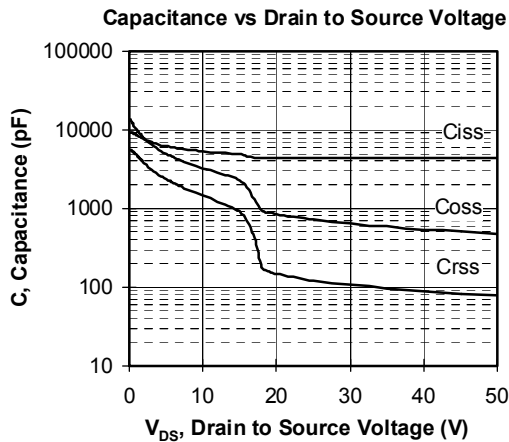
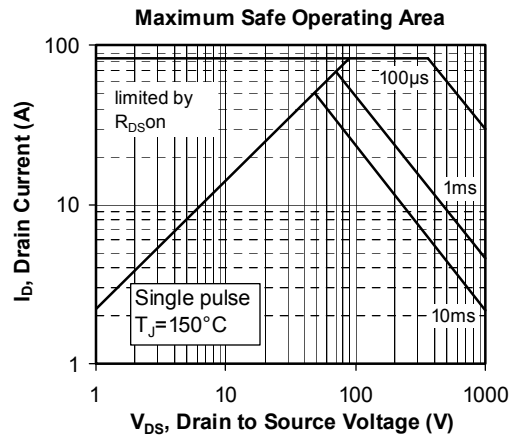
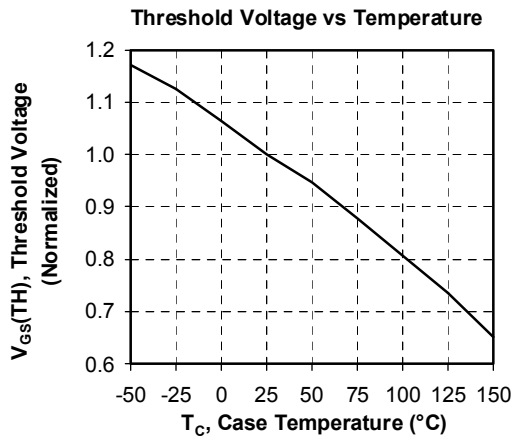
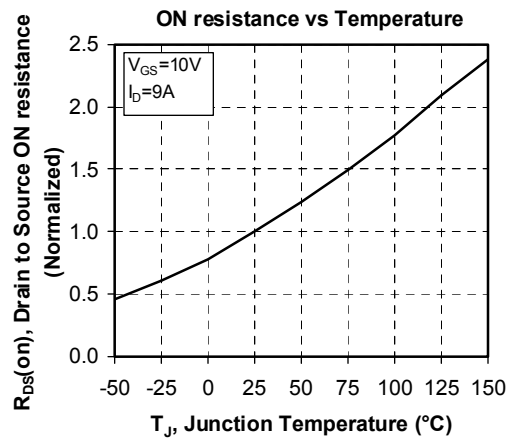
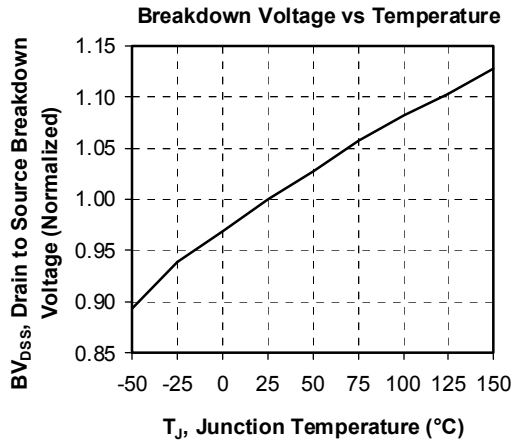
T: Thermistor temperature
 R_T : Thermistor value at T

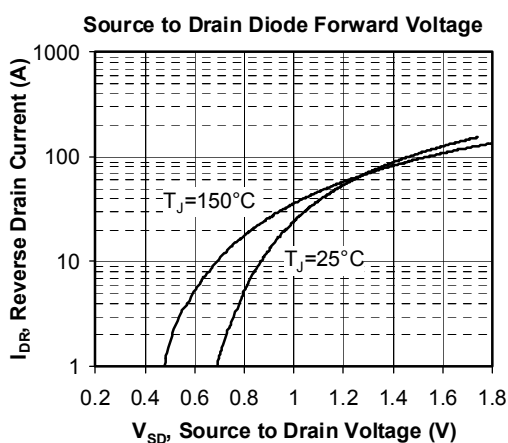
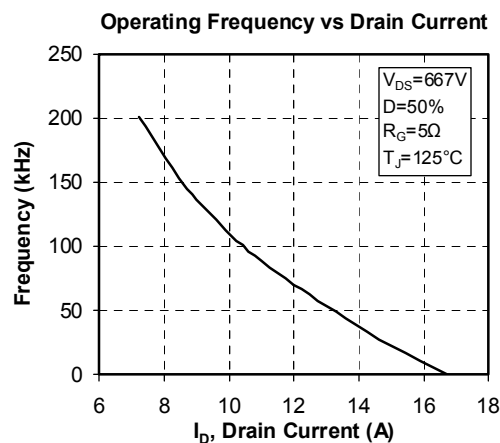
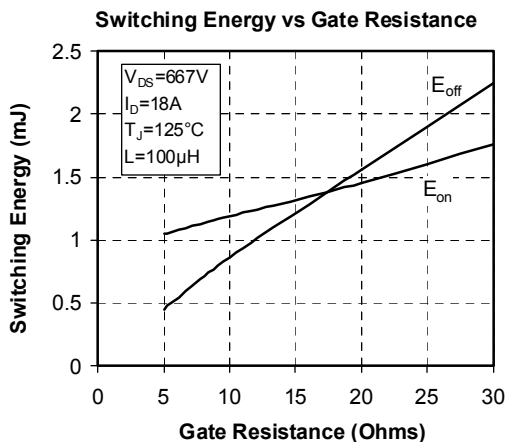
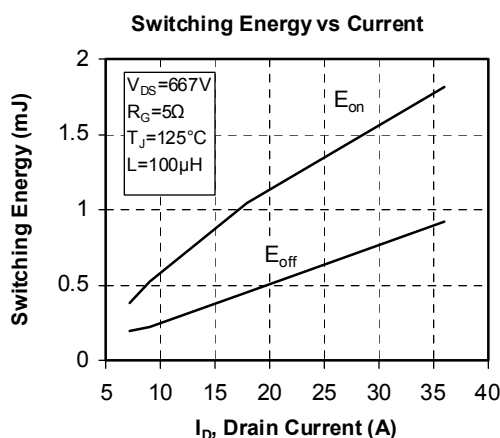
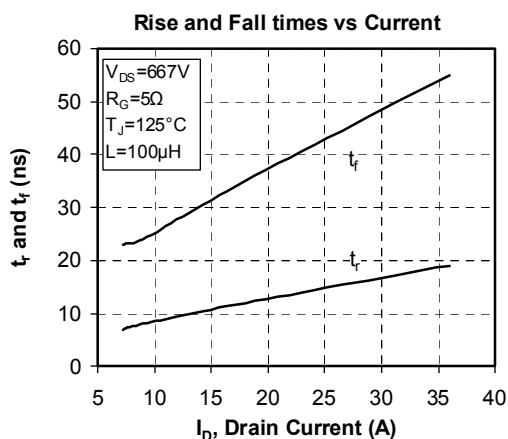
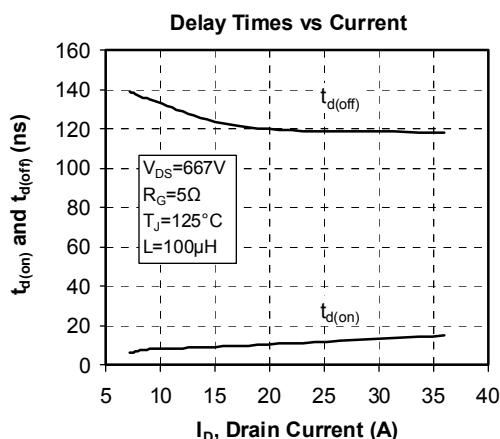
Package outline



Typical Performance Curve







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APT's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. U.S. and Foreign patents pending. All Rights Reserved.